

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.692848

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.007795 | 1000000 | 11250.6621094 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.192153 | 975000 | 277337.84375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.004730 | 24000 | 6826.89306641 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000059 | 300 | 85.15574646 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000138 | 700 | 199.177856445 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.197080 | 1000000 | 284449.0625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.010584 | 1000000 | 15276.2275391 | | |
| | | External Plating Total: | | | | 0.010584 | 1000000 | 15276.2275391 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001577 | 1000000 | 2276.11206055 | | |
| Internal Plating Total: | | | | 0.001577 | 1000000 | 2276.11206055 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001809 | 750000 | 2610.96191406 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000603 | 250000 | 870.320617676 | | |
| Die Attach Total: | | | | 0.002412 | 1000000 | 3481.2824707 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.048682 | 103000 | 70263.59375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.423013 | 895000 | 610542.1875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000945 | 2000 | 1363.93518066 | | |
| | | Encapsulation Total: | | | | 0.472640 | 1000000 | 682169.6875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000760 | 1000000 | 1096.92150879 | | |
| | | | | | TOTAL MASS (g) : | 0.692848 | | |